



LED

xLED

xLED-XIT-6050 Pin Fin LED Heat Sink Φ 60mm for Xicato

Features VS Benefits

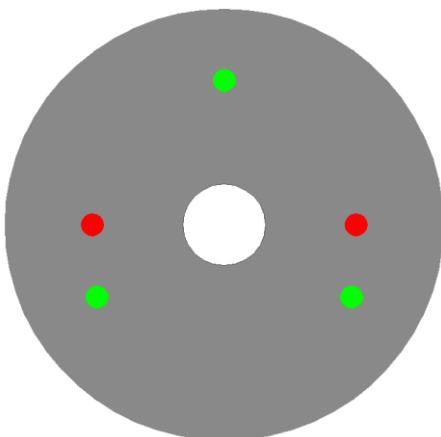
- * The xLED-XIT-6050 Xicato Pin Fin LED Heat Sinks are specifically designed for luminaires using the Xicato LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 900 to 2,200 lumen.
- * Thermal resistance range Rth 3.85°C/W.
- * Modular design with mounting holes foreseen for direct mounting of Xicato XSA/ XIM/ XTM modules.
- * Diameter 60.0mm - standard height 50.0mm, Other heights on request.
- * Forged from highly conductive aluminum.



Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of Seoul COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.

XICATO



Xicato LED Modules directly Mounting Options

Xicato XSM LED modules name :

- XSM8027-xxxx ; XSM9530-xxxx ;
- XSM8030-xxxx ; XSM9540-xxxx ;
- XSM8040-xxxx ; XSMV830-xxxx ;
- XSM9527-xxxx ;

Direct mounting with 3 screws M3 x 12mm;
Green indicator marks.

Xicato XIM LED modules name :

- XIM198027-xxx ; XIM198040-xxx ; XIM09-V9xxxxxx ;
- XIM198030-xxx ; XIM19V830-xxx ;
- XIM198035-xxx ; XIM0980 xxxxxx ;

Direct mounting with 3 screws M3 x 20mm;
Green indicator marks.

Xicato XTM LED modules:

- XTM19-8027-xxx ; XTM19-8040-xxx ; XTM0995 xxxxxx ;
- XTM19-8030-xxx ; XTM19-V830-xxx ;
- XTM19-8035-xxx ; XTM09-V9xxxxxx ;

Direct mounting with 3 screws M3 x 10mm;
Green indicator marks.

Direct mounting by Zhaga mounting holes with 2 screws M3 x 8mm;
Red indicator marks.

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Mounting Options and Drawings & Dimensions

Example: xLED-XIT-6050-M3-B-1

Example: xLED-XIT-6050-M3-**1** - **2**

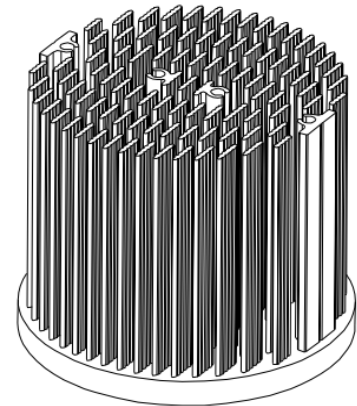
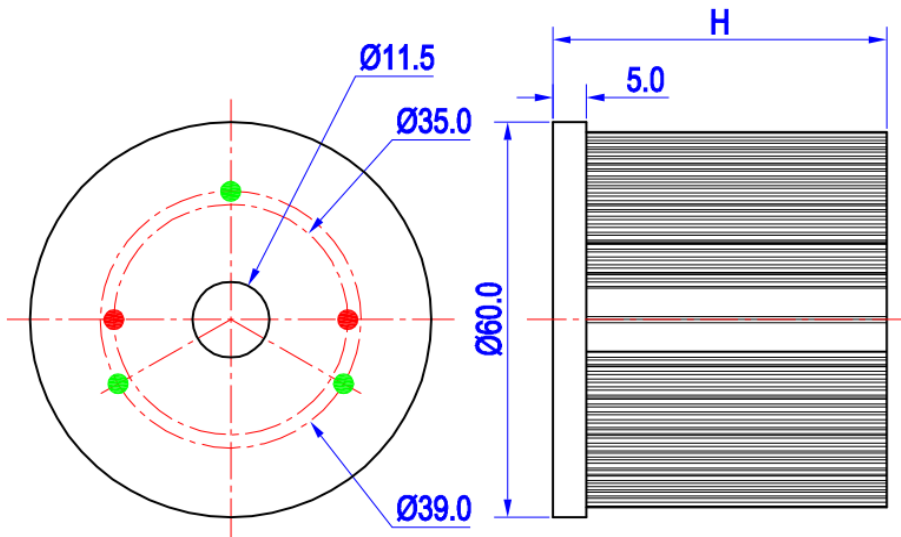
- 1** Anodising Color
 B-Black
 C-Clear
 Z-Custom

- 2** Mounting Options - see graphics for details Combinations available
 Ex.order code - 12
 means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	PART NUMBER	THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
N	xLED-XIT-6050-M3-#-N	M3	6.5mm	39.0mm/ 3-@120°
1	xLED-XIT-6050-M3-#-1	M3	6.5mm	35.0mm/ 2-@180° (Zhaga Book 3)
2	xLED-XIT-6050-M3-#-2	M3	Φ11.5mm	Through-Hole



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The product data table

	Model No.	xLED-XIT-6050
	Heatsink Size	Φ 60xH50mm
	Heatsink Material	AL1070
	Finish	Black Anodized
	Weight (g)	112.0
	Dissipated power (T_{hs-amb},50°C)	13.0 (W)
	Cooling surface area (mm²)	68473
	Thermal Resistance (R_{hs-amb})	3.85 (°C/W)

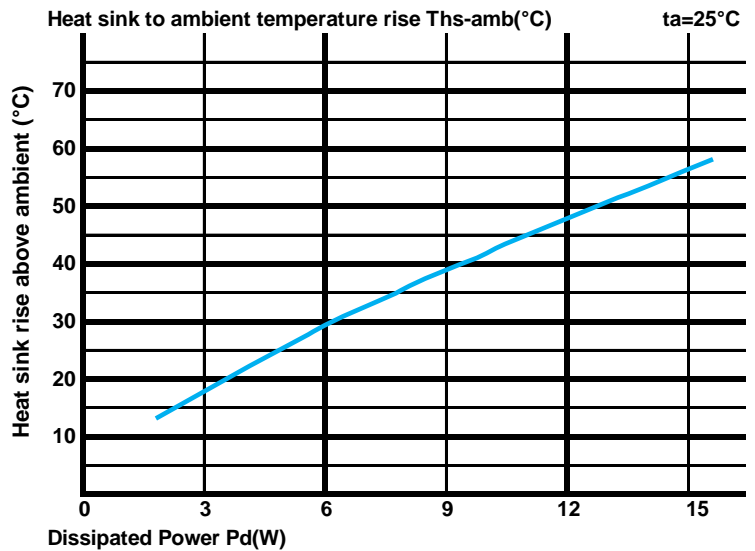
The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

* To calculate the dissipated power please use the following formula: $P_d = P_e \times (1 - \eta_L)$.

Pd - Dissipated power ; Pe - Electrical power ; η_L = Light efficiency of the LED module;

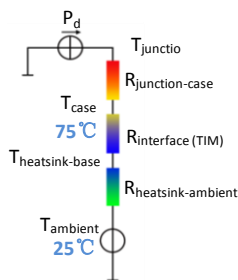
Dissipated Power Pd(W)	Pd = Pe x (1- η_L)	Heat sink to ambient thermal resistance R _{hs-amb} (°C/W)	Heat sink to ambient temperature rise T _{hs-amb} (°C)
		xLED-XIT-6050	
3.0		5.67	17.0
6.0		4.83	29.0
9.0		4.22	38.0
12.0		4.00	48.0
15.0		3.73	56.0



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (T_{hs} - T_a) / P_d$

θ - Thermal Resistance [°C/W]; T_{hs} - Heatsink temperature ; T_a - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is R_{amb-case}, the thermal resistance of the TIM outside the package is R_{case-TIM} [°C/W], the thermal resistance with the heat sink is R_{TIM-amb} [°C/W], and the ambient temperature is T_{amb} [°C].

*Thermal resistances outside the package R_{case-TIM} and R_{TIM-amb} can be integrated into the thermal resistance R_{case-amb} at this point. Thus, the following formula is also used:

$$T_{\text{junction}} = (R_{\text{amb-case}} + R_{\text{case-amb}}) \cdot P_d + T_{\text{amb}}$$